



Specification of Automotive MLCC

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C330JB81PNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 33pF, 50V, ±5%, C0G, 0603

• AEC-Q 200 Specified

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>330</u> <u>J</u> <u>B</u> <u>8</u> <u>1</u> <u>P</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor					
2	Size	0603 (inch code)	L:	$1.6 \pm 0.1 \text{ mm}$	W:	0.8 ± 0.1	mm
3	Dielectric	C0G		8 Inner electro	de Ni		
4	Capacitance	33 pF		Termination	Cu	l	
(5)	Capacitance	±5 %		Plating	Sn	100%	(Pb Free)
	tolerance			9 Product	Au	tomotive	
6	Rated Voltage	50 V		® Grade code	Sta	andard	
7	Thickness	0.8 ± 0.1 mm		11 Packaging	Ca	Cardboard Type, 7" reel(4,000ea)	

B. Reliability Test and Judgement condition

	Performance	Test condition		
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150°C		
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion		
	within ±2.5% or ±0.25pF whichever is larger			
	Q: 1000 min			
	IR : More than 10,000№ or 500№×μF			
	Whichever is Smaller			
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles		
	Capacitance Change :	Measurement at 24±2hrs after test conclusion		
	within ±2.5% or ±0.25pF whichever is larger	1 cycle condition :		
	Q: 1000 min	-55+0/-3 °C (15±3min) -> Room Temp(1min.)		
	IR : More than 10,000MΩ or 500MΩ×μF	-> 125+3/-0 °C (15±3min) -> Room Temp(1min.)		
	Whichever is Smaller			
Destructive Physical	No Defects or abnormalities	Per EIA 469		
Analysis				
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle		
	Capacitance Change :	Heat (25~65 ℃) and humidity (80~98%), Unpowered		
	within ±2.5% or ±0.25pF whichever is larger	measurement at 24±2hrs after test conclusion		
	Q: 350 min			
	IR : More than 10,000MΩ or 500MΩ×μF			
	Whichever is Smaller			
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85 ℃/85%RH, Rated Voltate and 1.3~1.5V,		
	Capacitance Change :	Add 100kohm resistor		
	within ±2.5% or ±0.25pF whichever is larger	Measurement at 24±2hrs after test conclusion		
	Q: 200 min	The charge/discharge current is less than 50mA.		
	IR : More than 500MΩ or 25MΩ×μF			
	Whichever is Smaller			
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125℃, 200% Rated Voltage,		
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion		
	within ±3.0% or ±0.3pF whichever is larger	The charge/discharge current is less than 50mA.		
	Q: 350 min			
	IR : More than 10,000№ or 500№×μF			
	Whichever is Smaller			

	Performance	Test condition		
External Visual	No abnormal exterior appearance	Microscope (´10)		
Physical Dimensions	Within the specified dimensions	Using The calipers		
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along		
	Capacitance Change :	3 mutually perpendicular axes of the test specimen (18 shocks)		
	within ±2.5% or ±0.25pF whichever is larger	Peakvalue Duration Wave Velocity		
	Q, IR: initial spec.	1,500G 0.5ms Half sine 4.7m/sec.		
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,		
	Capacitance Change :	Use 8"x5" PCB 0.031" Thick 7 secure points on one long side		
	within ±2.5% or ±0.25pF whichever is larger	and 2 secure points at corners of opposite sides. Parts mounted		
	Q, IR : initial spec.	within 2" from any secure point. Test from 10~2000Hz.		
Resistance to	Appearance : No abnormal exterior appearance	Solder pot : 260±5 ℃, 10±1sec.		
Solder Heat	Capacitance Change :			
	within ±2.5% or ±0.25pF whichever is larger			
	Q, IR : initial spec.			
Thermal Shock	Appearance : No abnormal exterior appearance	-55 ℃/+125 ℃.		
	Capacitance Change :	Note: Number of cycles required-300,		
	within ±2.5% or ±0.25pF whichever is larger	Maximum transfer time-20 sec, Dwell time-15min. Air-Air		
Q, IR : initial spec.				
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002		
	Capacitance Change :			
	within ±2.5% or ±0.25pF whichever is larger			
	Q, IR : initial spec.			
Solderability	95% of the terminations is to be soldered	a) Preheat at 155 ℃ for 4 hours, Immerse in solder for 5s at 245±5 ℃		
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C		
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C		
		solder : a solution ethanol and rosin		
Electrical	Capacitance : Within specified tolerance	The Capacitance /Q should be measured at 25 ℃,		
Characterization	Q: 1000 max.	1Mb±10%, 0.5~5Vrms		
	IR(25 °C): More than 100,000 MΩ or 1,000 MΩ×μF	I.R. should be measured with a DC voltage not exceeding		
	IR(125℃) : More than10,000MΩ or 100MΩ×μF	Rated Voltage @25°C, @125°C for 60~120 sec.		
	Whichever is Smaller	Dielectric Strength: 250% of the rated voltage for 1~5 seconds		
Board Flex	Dielectric Strength	Danding to the limit (2) \ for E accords		
Board Flex	Appearance : No abnormal exterior appearance	Bending to the limit (3mm) for 5 seconds		
	Capacitance Change :			
Terminal	within ±5.0% or ±0.5pF whichever is larger Appearance: No abnormal exterior appearance	10N, for 60±1 sec.		
Strength(SMD)	Capacitance Change :	1014, 101 00±1 350.		
Strength(SMD)	within ±2.5% or ±0.25pF whichever is larger			
Beam Load	Destruction value should not be exceed	Beam speed		
Stall Load	Chip Length < 2.5mm	0.5±0.05mm/sec		
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	a) Chip Thickness > 0.5mm : 20N			
Temperature	b) Chip Thickness ≤ 0.5mm : 8N COG			
Characteristics	(From -55℃ to 125℃, Capacitance change should	he within +30PPM/℃)		
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C. Recommended Soldering method :

Meet IPC/JEDEC J-STD-020 D Standard

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.